

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3350460

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	CHIH-KUNG HUANG	05/08/2015
	WEI-JEN LAI	05/08/2015
	WEN-CHUN LIU	05/08/2015
RECEIVING PARTY DATA		
Name:	IBIS INNOTECH INC.	
Street Address:	58,CHAOMA 7TH STREET, SITUN DIST.,	
City:	TAICHUNG CITY	
State/Country:	TAIWAN	
Postal Code:	40757	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	14663447	
CORRESPONDENCE DATA		
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ATTORNEY DOCKET NUMBER:	52117-US-PA	
NAME OF SUBMITTER:	BELINDA LEE	
SIGNATURE:	/Belinda Lee/	
DATE SIGNED:	05/12/2015	
Total Attachments: 2		
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ASSIGNMENT

WHEREAS,

1. Chih-Kung Huang
2. Wei-Jen Lai
3. Wen-Chun Liu

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **PACKAGE SUBSTRATE STRCUTURE**

[] Filed: 03/19/2015 Serial No. 14/663,447

[x] Executed concurrently with the execution of this instrument

WHEREAS 1. IBIS Innotech Inc.
of 58,Chaoma 7th Street, Situn Dist., Taichung City 40757, Taiwan

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Chih-Kung Huang

Date: MAY 08 2015

Sole or First Joint Inventor: Chih-Kung Huang

Signature: Wei-Jen Lai

Date: MAY 08 2015

Second Joint Inventor (if any): Wei-Jen Lai

Signature: Wen-Chun Liu

Date: MAY 08 2015

Third Joint Inventor (if any): Wen-Chun Liu